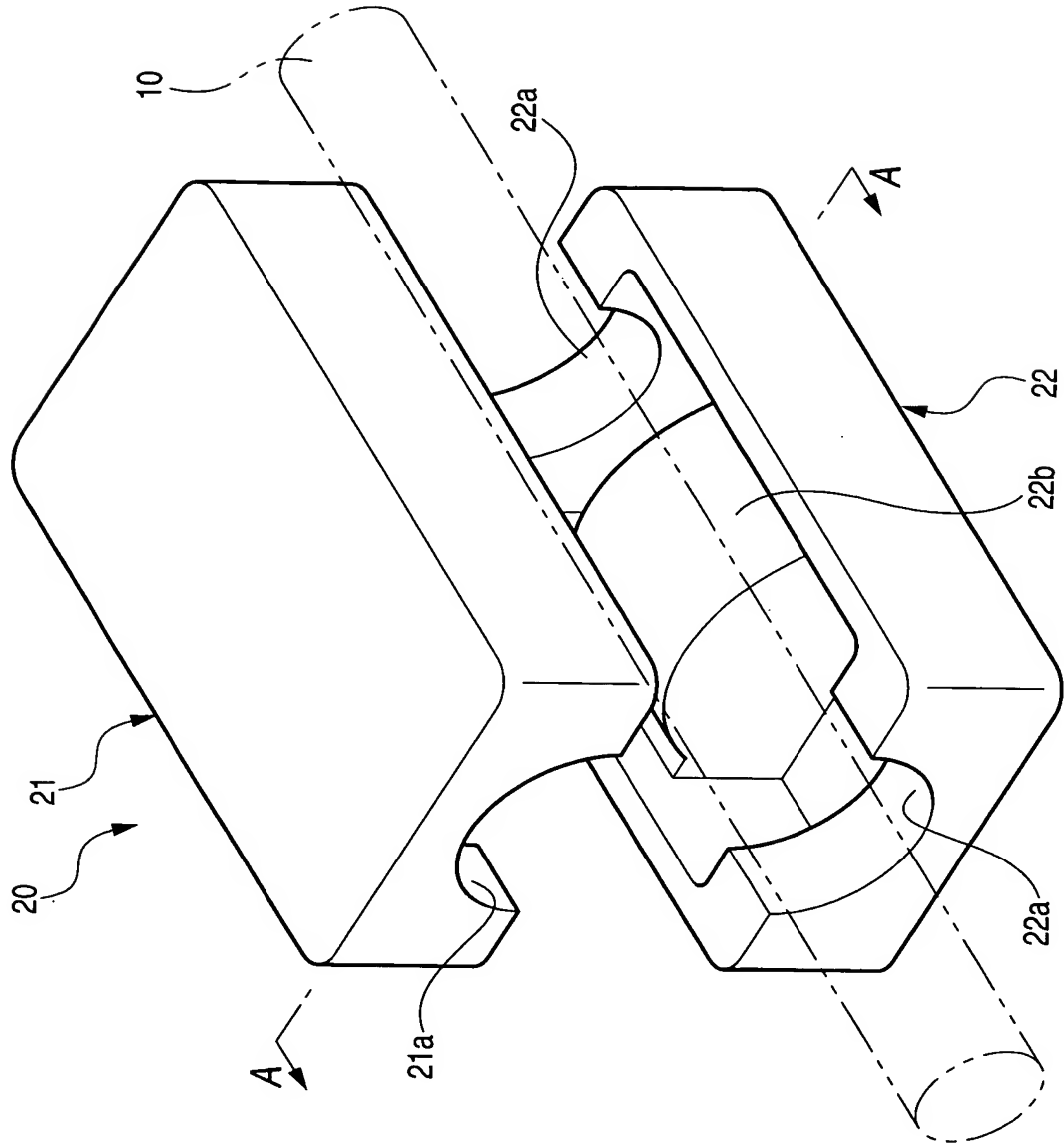


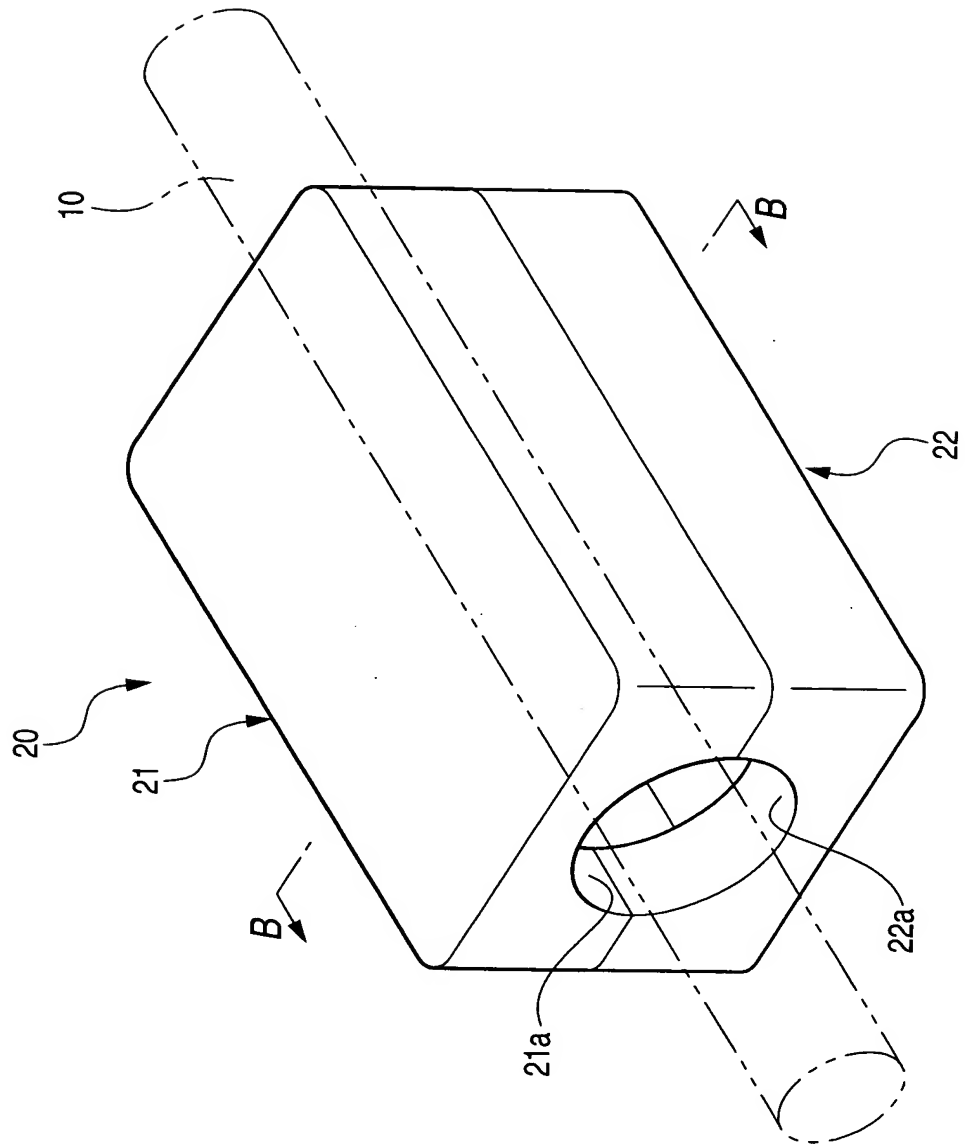


FIG. 1



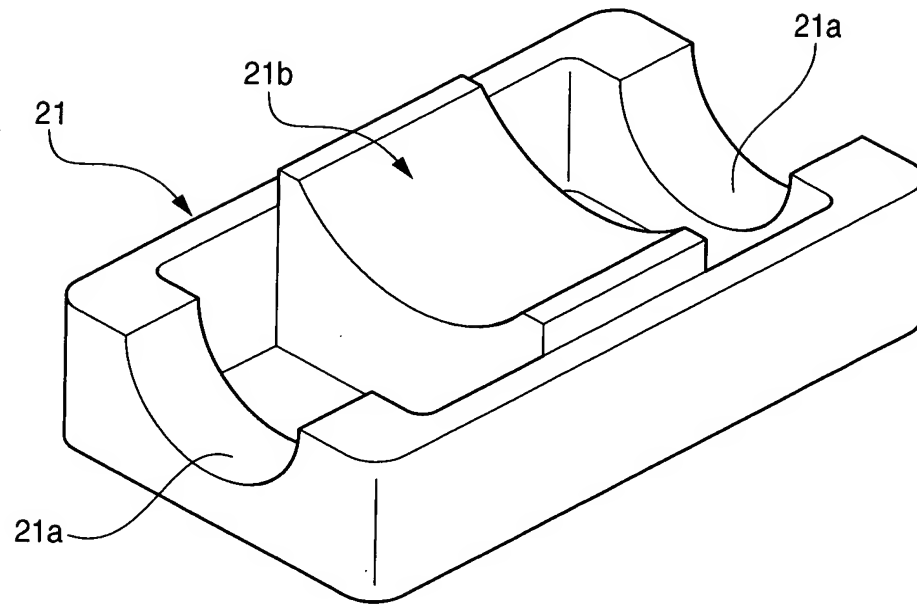
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FIG. 2

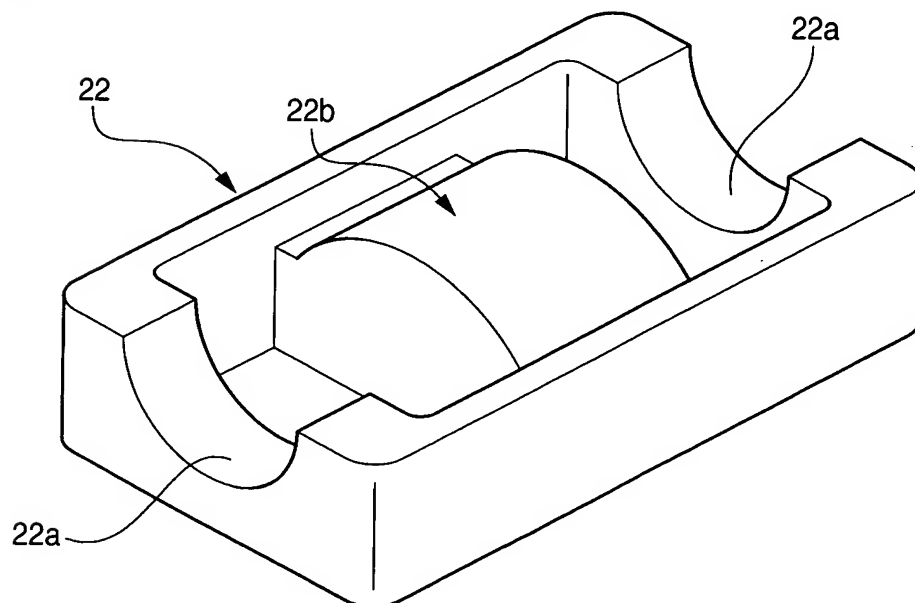


This diagram shows a second embodiment of the device, labeled 20. It features a second substrate 21 with a second opening 22. A second conductive layer 22b is formed on the inner surface of the second opening 22. A second conductive paste 10a is applied to the second conductive layer 22b, forming a second conductive paste layer 10. The second conductive paste 10a is shown as a circular area with a cross-hatched pattern, similar to the first embodiment. The second substrate 21 is shown with diagonal hatching, and the second opening 22 is a semi-circular recess.

**FIG. 4**



**FIG. 5**



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FIG. 6

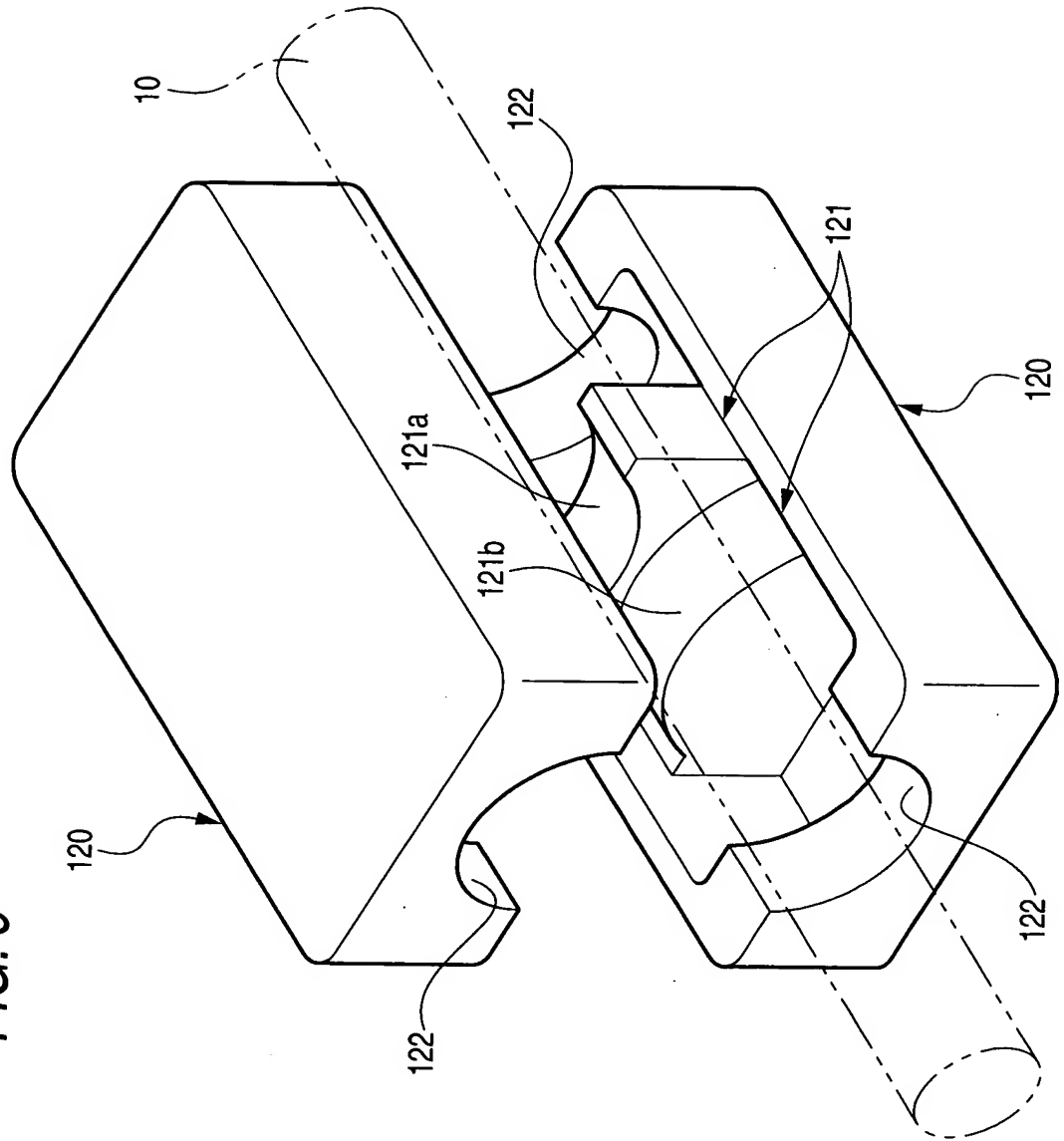
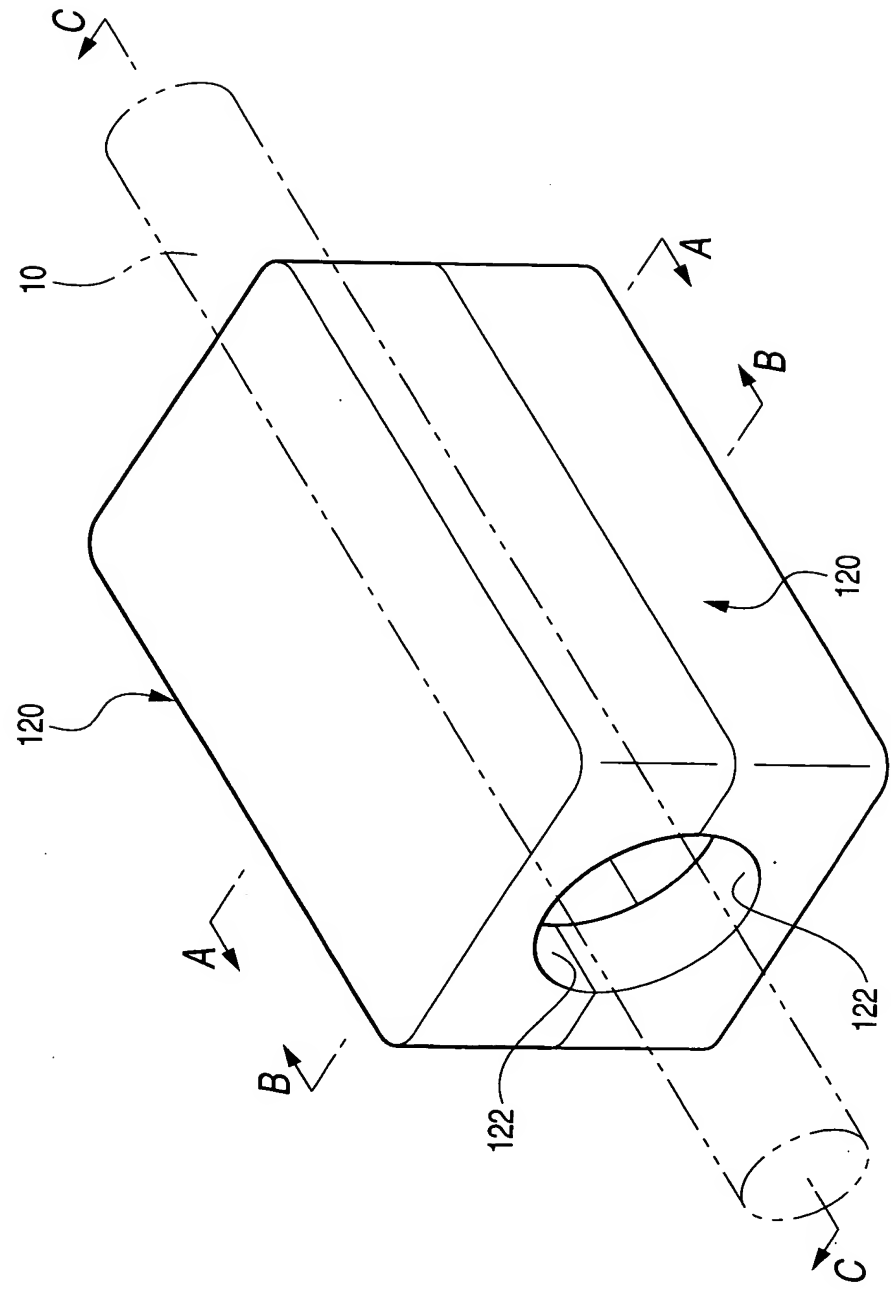
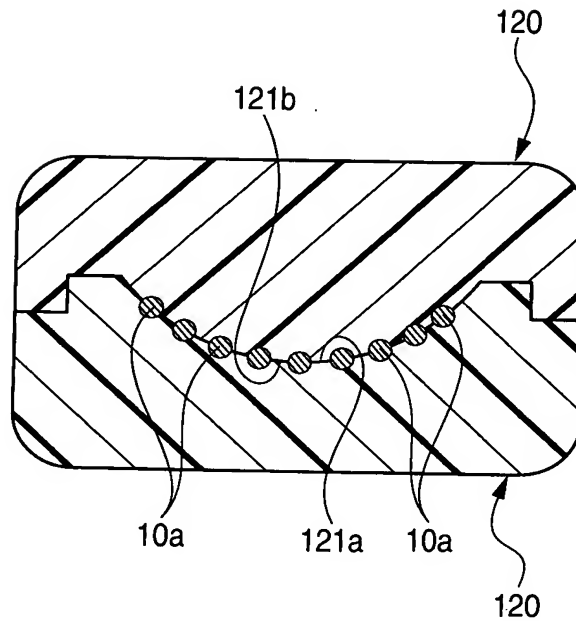


FIG. 7

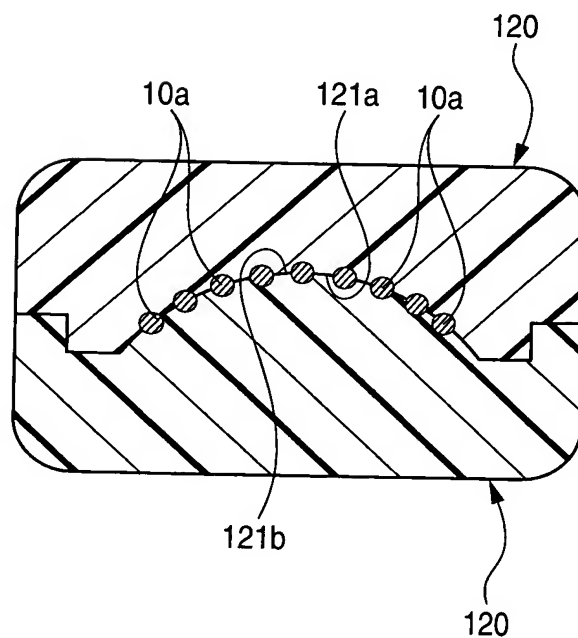


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*FIG. 8*

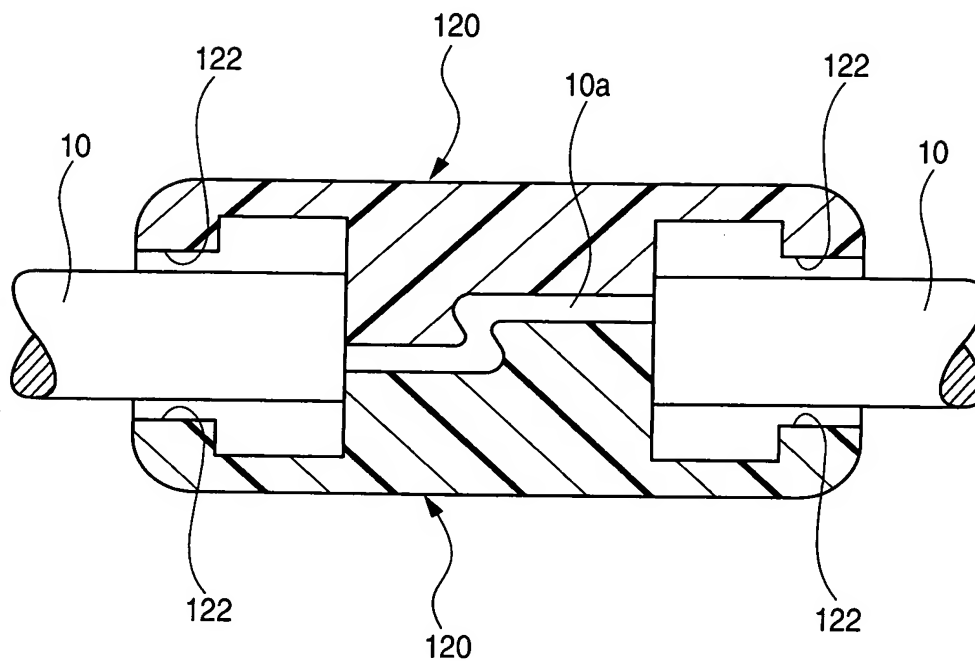


*FIG. 9*

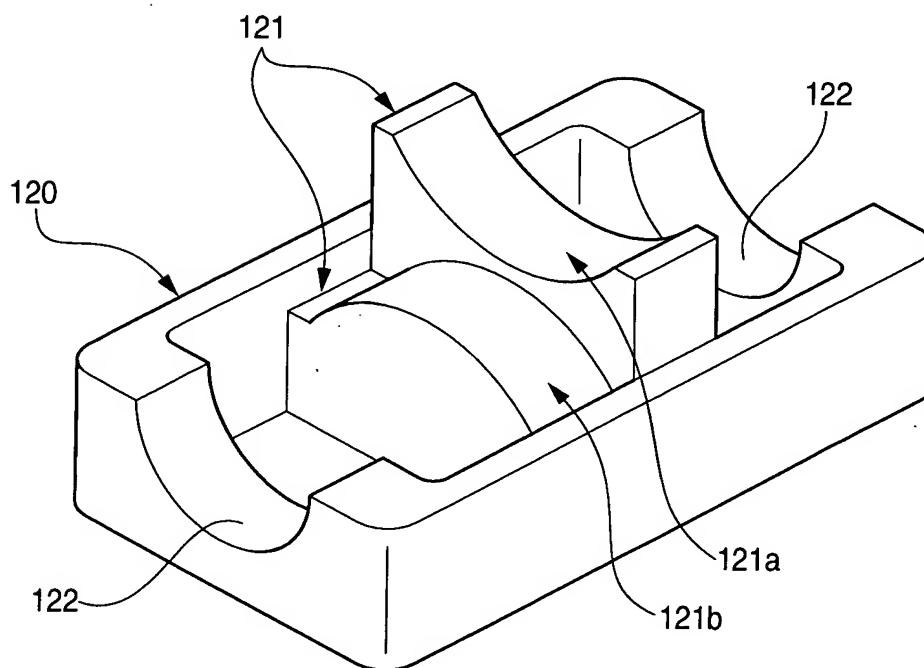


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**FIG. 10**

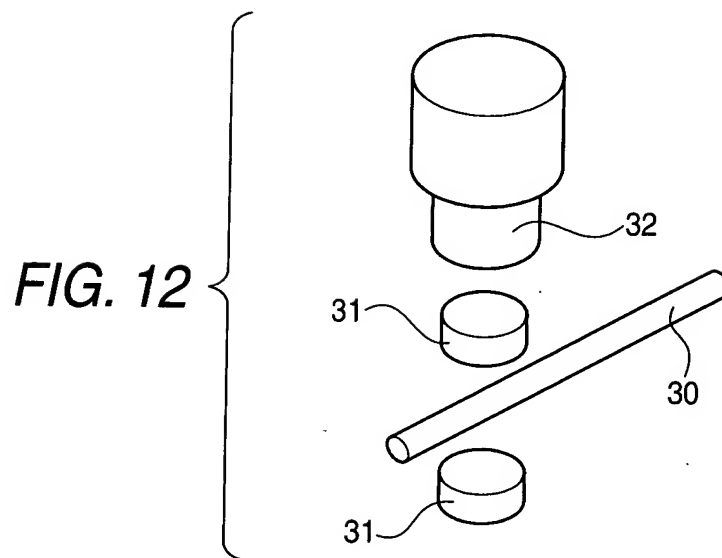


**FIG. 11**

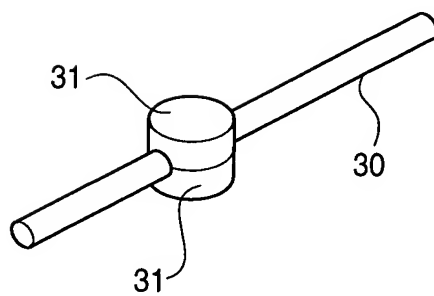




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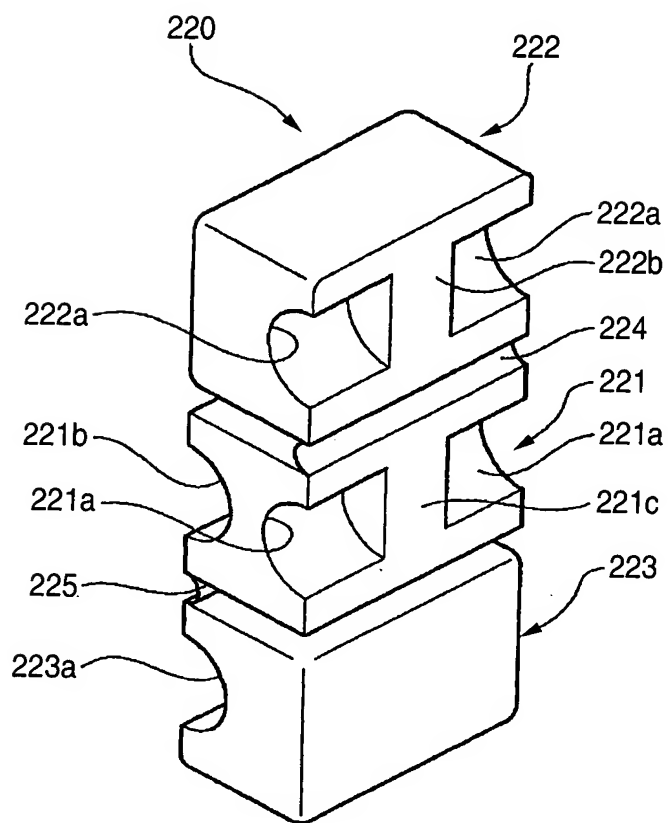


**FIG. 13**



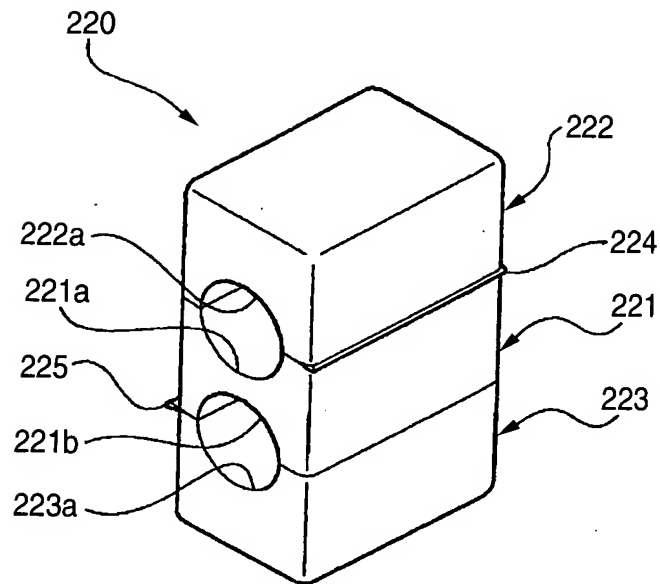
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**FIG. 14**



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**FIG. 15**



**FIG. 16**

